| © Copyright                          | Composition De<br>2005. IPC, Bannock<br>and Pan-American c  | burn, Illinois. A     | Il rights reserved nations. | under both             | This docume<br>level parts, t                                      | ent is a declarat                         | ion of the su<br>encompasse   | ibstances v<br>s all lower | vithin the manufact<br>level materials for | urer listed which the r | tem. Note:<br>nanufacture       | if the item is an as<br>er has engineering | ssembly with low responsibility. |  |
|--------------------------------------|---|-----------------------|-----------------------------|------------------------|--|---|-------------------------------|----------------------------|--|-------------------------|---------------------------------|--|----------------------------------|--|
|                                      | IPC Web Site for Information on IPC-1752 Standard Form Ty<br>http://www.ipc.org/IPC-175x Distribu |                       |                             |                        | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materi |   |                               |                            | erials and N                               | als and Mfg Information |                                 |  |                                  |  |
| Supplier Information                 |   |                       |                             |                        |  |   |                               |                            |  |                         |                                 |  |                                  |  |
| Company name* Compa                  |   |                       | ompany unique ID            |                        |  | Unique ID Authority                       |                               |                            |  | Respon                  | Response Date*                  |  |                                  |  |
| onsemi                               |   |                       |                             |                        |  |   |                               |                            |  | 2025-05                 | 2025-05-14                      |  |                                  |  |
| Contact Name Title                   |   |                       | Title - Contact             |                        |  | Phone - Contact*                          |                               |                            |  | Email -                 | Email - Contact*                |  |                                  |  |
| Product-Env-Stewards Prod            |   |                       | Product Enviro Compliance   |                        |  | NA  |                               |                            |  | Produc                  | Product-Env-Stewards@onsemi.com |  |                                  |  |
| Authorized Representative* Title - R |   |                       | e - Representative          |                        |  | Phone - Representative*                   |                               |                            |  | Email -                 | Email - Representative*         |  |                                  |  |
| Product-Env-Stewards Product E       |   |                       | uct Enviro Compliance       |                        |  | NA  |                               |                            |  | Produc                  | Product-Env-Stewards@onsemi.com |  |                                  |  |
| Requester Item Number                | ster Item Number Mfr Item Nu  |                       | Number Mfr Item Name        |                        |  | Effective Date                            | te Version Manufacturing Site |                            |  | Weight*                 | UOM                             | Unit Type                                  |                                  |  |
|                                      | MC74V<br>G  | MC74VHCT50ADR2 LOG CM |                             | OG CMOS BUFR NINVERT   |  | 2025-05-14                                |                               | P                          | PH1  |                         | 122.05                          | mg   | Each                             |  |
| Aanufacturing Proccess Inf           | ormation  |                       |                             |                        |  |   |                               |                            |  |                         |                                 |  |                                  |  |
| Terminal Plating / Grid A            | Terminal Plating / Grid Array Material Terminal Base  |                       | Alloy                       | y J-STD-020 MSL Rating |  | Peak Process Body Temperature Max Time at |                               | e Max Time at Pea          | ak Temperature Number of Reflow Cycles     |                         |                                 |  |                                  |  |
| Matte Tin (Sn) - annealed            |   | CU Alloy              | U Alloy 1                   |                        |  | 260 C                                     |                               | С                          | 30 seco                                    |                         | nds 3                           |  |                                  |  |
| omments                              |   |                       |                             |                        |  |   |                               |                            |  |                         |                                 |  |                                  |  |
| vel 1 - maximum time at peak ten     | nperature during so   | oldering is 10-3      | 0 seconds                   |                        |  |   |                               |                            |  |                         |                                 |  |                                  |  |
| or more information regarding m      | aterial composition   | please refer to       | page 3                      |                        |  |   |                               |                            |  |                         |                                 |  |                                  |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance           | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|---------------------|------------------|--------|---------|-----------------|
| Die                  | 0.98   | mg              | Supplier | Silicon (Si)        | 7440-21-3        |        | 0.98    | mg              |
| Die Attach           | 4.44   | mg              | Supplier | Silver (Ag)         | 7440-22-4        |        | 3.33    | mg              |
|                      |        |                 | Supplier | Epoxy resins        | 129915-35-1      |        | 1.11    | mg              |
| Lead Frame           | 69.62  | mg              | Supplier | Silver (Ag)         | 7440-22-4        |        | 0.7658  | mg              |
|                      |        |                 | Supplier | Zinc (Zn)           | 7440-66-6        |        | 0.0835  | mg              |
|                      |        |                 | Supplier | Iron (Fe)           | 7439-89-6        |        | 1.6361  | mg              |
|                      |        |                 | Supplier | Copper (Cu)         | 7440-50-8        |        | 67.1137 | mg              |
|                      |        |                 | Supplier | Phosphorus (P)      | 7723-14-0        |        | 0.0209  | mg              |
| Mold Compound-Black  | 43.43  | mg              |          | Epoxy Phenol Resin  | proprietary data |        | 4.5601  | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2) | 60676-86-0       |        | 38.8699 | mg              |
| Plating              | 3.27   | mg              | Supplier | Tin (Sn)            | 7440-31-5        |        | 3.27    | mg              |
| Wire Bond - Au       | 0.31   | mg              | Supplier | Gold (Au)           | 7440-57-5        |        | 0.31    | mg              |